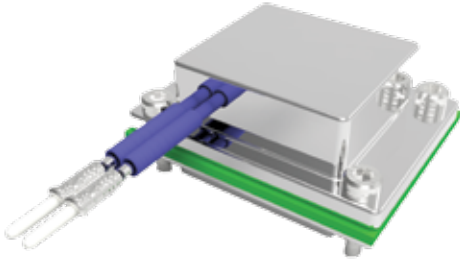


Amphenol CTF-MEZZ-10G-1



FEATURES AND BENEFITS

- + 1 Channel (1 Tx, 1 Rx)
- + Small Form Factor - Mezzanine card
- + 10.3125 Gbps
- + Built-in test
- + 12 dB worst case between transmit power and receive
- + Up to 10G Ethernet, 8G Fibre Channel, PCI-Express 3.0, DVI and more

FIBER INTERFACE

- + M29504 Termini - Bring fiber easily to your D38999 receptacle

BOARD LEVEL COPPER INTERFACE

- + Samtec Edge Rate™ rugged connector for signal and power (Consult factory for other options)

POWER SPECIFICATIONS

- + 5V power connection via Samtec Edge Rate™
- + Less than 5 watts power consumption

RUGGEDIZATION

- + Natural convection cooled (no fan)
- + Operational temperature -40°C to +85°C
- + Integrated Frame/Heatsink

CONTACT US:

Jared Sibrava

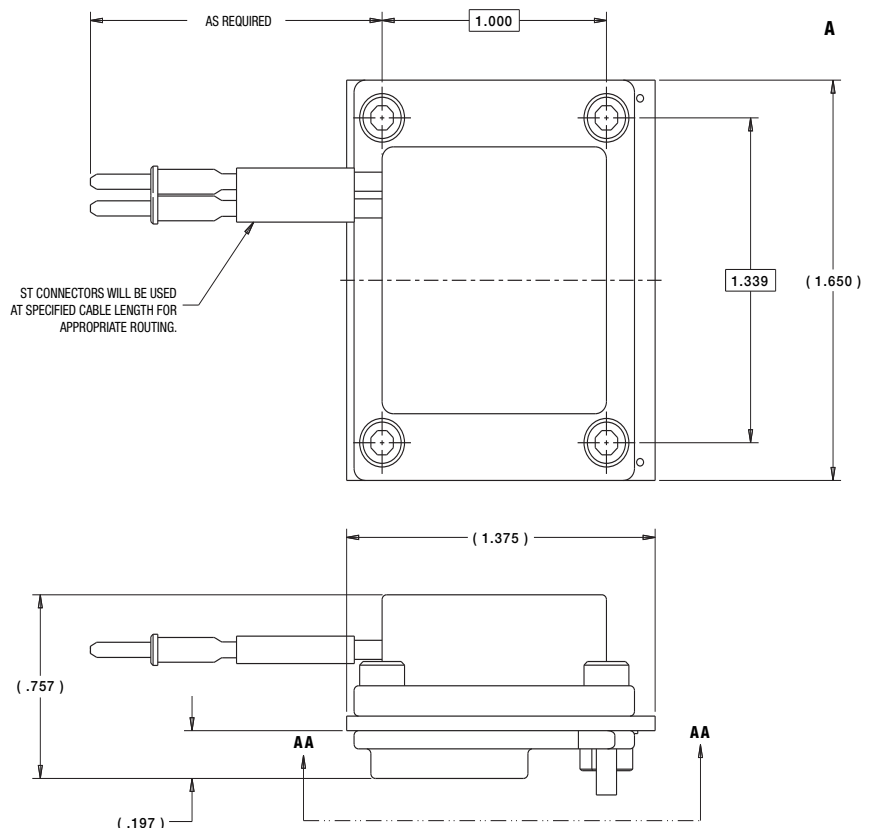
E-mail: jsibrava@amphenol-aao.com

Phone: 607-643-1845

OVERVIEW

Amphenol Aerospace adds the CTF-MEZZ-10G-1 to the CTF (Copper to Fiber) Integrated Electronic Products Family. This product line is rugged, flexible, and affordable with many configuration options available.

CTF-MEZZ-10G-1 is an integrated media converter that couples high speed copper technology with M29504 fiber technology. Now you can transfer high speed data seamlessly from copper to fiber and fiber to copper. Integrate easily with your front panel, back panel, or daughtercard.



Ordering Guide

Ordering procedure is shown below using part number CTF-

1. 2. 3. 4.

Connector Type	Material	Copper Interface	Finish
CTF			

Step 1. Connector Type

	Designates
CTF	CTF Product Family

Step 2. Select a Material

	Designates
-5	Aluminum Shell
-6	Composite Shell
-8	Stainless Steel Shell

Step 3. Select a Copper Interface

	Designates
S	Samtec Edge Rate™ Connector

Step 4. Select a Finish

	Designates
T	Aluminum Durmalon
Z	Aluminum Black Zinc Nickel
F	Aluminum Electroless Nickel
M	Composite Electroless Nickel
W	Aluminum OD Cad
J	Composite OD Cad
L	Stainless Steel Electrodeposited Nickel
Y	Stainless Steel Passivated



Available Test Equipment

	Part Number	Description
Test Cable	CF-980062-019	LC Fiber Optic Test Cable for D38999 Connector
Test Board	CF-980062-016	SMA Test Board for Samtec Connector

CONTACT US:

Jared Sibrava

E-mail: jsibrava@amphenol-ao.com

Phone: 607-643-1845

Overview

Amphenol integrated electronic products are designed and manufactured to our Ruggedization guidelines listed below. These guidelines ensure years of reliable operation in harsh environment applications where extreme operating temperatures, shock, vibration and corrosive atmospheres are regularly experienced

Temperature

- Operating Temperature - Thermal Cycles between -40°C and 85°C while device is operating
- Temperature is measured at chassis housing or card edge
- Storage Temperature - Thermal Cycles between -55°C and 125°C

Humidity

- Operating Humidity – Humidity cycle between 0-100% non-condensing humidity while device is operating
- Storage Humidity – Humidity cycle between 0-100% condensing humidity

Sealing

- Sealing can be optionally provided at the MIL-DTL-38999 interface with up to 10-5 cc/sec performance

Fluids Susceptibility

- MIL-DTL-38999 receptacle interface per EIA-364-10E

Vibration & Shock

- Sine Vibration – 10 g Peak, 5-2,000Hz
 - Based on a sine sweep duration of 10 minutes per axis in each of three mutually perpendicular axes. May be displacement limited from 5 to 44 Hz, depending on specific test.
- Random Vibration - 0.005@5Hz, 0.1@15Hz, 0.1@2,000Hz
 - 60 minutes per axis, in each of three mutually perpendicular axes.
- 40 G Peak Shock Cycle
 - Three hits in each axis, both directions, ½ sine and terminal-peak saw tooth, Total 36 hits.

Altitude

- -1,500 to 60,000 ft Altitude Testing w/ Rapid Depressurization

Electromagnetic Compatibility

- Designed to comply with MIL-STD-461E

Printed Circuit Board Assemblies

- Conformal Coat
 - Amphenol performs Conformal Coating to both sides of printed circuit board assemblies using HUMISEAL IB31 in accordance with IPC-610, Class 3.
- Printed Circuit Board Rigidity
 - Amphenol printed circuit boards are fabricated in accordance with IPC-6012, Class 3.
- Printed Circuit Board Fabrication
 - Amphenol printed circuit boards acceptance criteria is in accordance with IPC-610, Class 3.

Reliability Predictions (MTBF)

Amphenol can perform Mean Time Between Failure (MTBF) reliability analysis in full compliance with MIL-HDBK-217F-1 Parts Count Prediction and MIL-HDBK-217F-1 Parts Stress Analysis Prediction. We can also perform reliability analyses in full compliance of ANSI/VITA 51.1 if it is required or preferred over the later method.

CONTACT US:

Jared Sibrava

E-mail: jsibrava@amphenol-aa.com

Phone: 607-643-1845

Notice: Specifications are subject to change without notice. Contact your nearest Amphenol Corporation Sales Office for the latest specifications. All statements, information and data given herein are believed to be accurate and reliable but are presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements or suggestions concerning possible use of our products are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should assume that all safety measures are indicated or that other measures may not be required. Specifications are typical and may not apply to all connectors.

AMPHENOL is a registered trademark of Amphenol Corporation. ©2015 Amphenol Corporation REV:1/28/2015